

VQ2004 SERIES

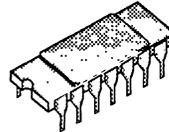


P-Channel Enhancement-Mode MOS Transistor Arrays

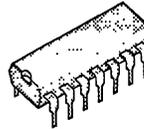
PRODUCT SUMMARY

PART NUMBER	$V_{(BR)DSS}$ (V)	$r_{DS(ON)}$ (Ω)	I_D (A)	PACKAGE
VQ2004J	-60	5	-0.41	Plastic
VQ2004P	-60	5	-0.41	Side Braze

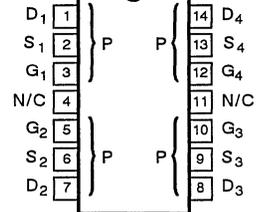
14-PIN DIP
SIDE BRAZE



14-PIN PLASTIC



TOP VIEW
Dual-In-Line Package



Performance Curves: VPDV10 (See Section 7)

ABSOLUTE MAXIMUM RATINGS ($T_A = 25^\circ\text{C}$ unless otherwise noted)

PARAMETERS/TEST CONDITIONS	SYMBOL	VQ2004J	VQ2004P	UNITS
Drain-Source Voltage	V_{DS}	-60	-60	V
Gate-Source Voltage	V_{GS}	± 30	± 20	
Continuous Drain Current	I_D	$T_A = 25^\circ\text{C}$	-0.41	A
		$T_A = 100^\circ\text{C}$	-0.23	
Pulsed Drain Current ¹	I_{DM}	± 3	± 3	
Power Dissipation - Single	P_D	$T_A = 25^\circ\text{C}$	1.3	W
		$T_A = 100^\circ\text{C}$	0.52	
Power Dissipation - Quad	P_D	$T_A = 25^\circ\text{C}$	2	
		$T_A = 100^\circ\text{C}$	0.8	
Operating Junction and Storage Temperature	T_J, T_{stg}	-55 to 150		$^\circ\text{C}$
Lead Temperature (1/16" from case for 10 seconds)	T_L	300		

THERMAL RESISTANCE

THERMAL RESISTANCE	SYMBOL	VQ2004J	VQ2004P	UNITS
Junction-to-Ambient - Single	R_{thJA}	96.2	96.2	$^\circ\text{C}/\text{W}$
Junction-to-Ambient - Quad		62.5	62.5	

¹Pulse width limited by maximum junction temperature.

ELECTRICAL CHARACTERISTICS ¹				LIMITS		
PARAMETER	SYMBOL	TEST CONDITIONS	TYP ²	VQ2004 ⁴		UNIT
				MIN	MAX	
STATIC						
Drain-Source Breakdown Voltage	$V_{(BR)DSS}$	$V_{GS} = 0\text{ V}, I_D = -10\ \mu\text{A}$	-110	-60		V
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}, I_D = -1\text{ mA}$	-3.4	-2	-4.5	
Gate-Body Leakage	I_{GSS}	$V_{DS} = 0\text{ V}$ $V_{GS} = \pm 30\text{ V}$ $T_J = 125^\circ\text{C}$	± 1 ± 5		± 100 ± 500	nA
Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS} = -60\text{ V}$ $V_{GS} = 0\text{ V}$ $T_J = 125^\circ\text{C}$	-0.0005 -0.1		-10 -500	μA
On-State Drain Current ³	$I_{D(ON)}$	$V_{DS} = -10\text{ V}, V_{GS} = -10\text{ V}$	-2	-1		A
Drain-Source On-Resistance ³	$r_{DS(ON)}$	$V_{GS} = -10\text{ V}$ $I_D = -1\text{ A}$ $T_J = 125^\circ\text{C}$	2.5 4.3		5 8	Ω
Forward Transconductance ³	g_{FS}	$V_{DS} = -10\text{ V}, I_D = -0.5\text{ A}$	325	200		mS
Common Source Output Conductance ³	g_{OS}	$V_{DS} = -7.5\text{ V}, I_D = -0.1\text{ A}$	450			μS
DYNAMIC						
Input Capacitance	C_{iss}	$V_{DS} = -25\text{ V}$ $V_{GS} = 0\text{ V}$ $f = 1\text{ MHz}$	75		150	pF
Output Capacitance	C_{oss}		40		60	
Reverse Transfer Capacitance	C_{rss}		18		25	
SWITCHING						
Turn-On Time	$t_{d(ON)}$	$V_{DD} = -25\text{ V}, R_L = 47\ \Omega$ $I_D = -0.5\text{ A}, V_{GEN} = -10\text{ V}$ $R_G = 25\ \Omega$ (Switching time is essentially independent of operating temperature)	11		15	ns
	t_r		30		40	
Turn-Off Time	$t_{d(OFF)}$		20		30	
	t_f		20		30	

- NOTES: 1. $T_A = 25^\circ\text{C}$ unless otherwise noted.
2. For design aid only, not subject to production testing.
3. Pulse test; $PW = 300\ \mu\text{s}$, duty cycle $\leq 2\%$.
4. Data sheet limits have been revised.